RoHS 🗭 SL1011A/SL1011B/SL1411A Series



Agency Approvals

AGENCY	AGENCY FILE NUMBER
"91	E128662

2 Electrode GDT Graphical Symbol

ittelfuse

Expertise Applied | Answers Delivered



Description

The SL1011A/SL1011B/SL1411A series provides high levels of protection against fast rising transients in the 100V/µs to 1kV/µs range usually caused by lightning disturbances.

The SL1011A/SL1011B/SL1411A series offers low capacitance (< 1.5pf) which provides low insertion loss at high frequencies.

SL1011A offers 5kA protection without destruction whereas the SL1011B and SL1411A offer 10kA surge protection without destruction (maximum single surge of 12kA @ 8/20µs).

Features

- RoHS compliant
- Low insertion loss
- Excellent response to fast rising transients
- Ultra low capacitance

Applications

- Broadband equipment
- ADSL equipment
- XDSL equipment
- Satellite and CATV equipment

 5kA (SL1011A) or 10kA (SL1011B & SL1411A)

surge capability tested

pulse as defined by

• General telecom equipment

with 8/20µs

IEC 61000-4-5

B

Gas Plasma Arrester (GDT) Products SL1011A/SL1011B/SL1411A Series



Electrical Characteristics

	Device Specifications (at 25°C)						Life Ratings																			
Part Number	DC E ir ((Breakc NVolts @100V/	down , ^{1,2} (s)	Impulse Breakdown in Volts ³ (@100V/µs)	Impulse Breakdown In Volts (@1kV/µs)	Insulation Resistance	Capaci- tance (@1MHz)	Arc Voltage (on state Voltage) @1Amp Min	Surge Life (@100A 10/1000µs)	Nominal Impulse Discharge Current (8/20µs)	Nominal AC Discharge Current (10x1s @50-60Hz)	AC Dischage Current (9 Cycles @ 50Hz)	DC Holdover Voltage⁴	Max I Discharg (1 App	mpulse ge Current lication)											
	MIN	TYP	MAX	MAX		MIN	MAX	ТҮР					ТҮР	@ 8/20µs	@ 10/350µs											
SL1011A075																										
SL1011B075	60	75	90	500	700																					
SL1411A075						10 ¹⁰ Ω																				
SL1011A090						(at 50V)																				
SL1011B090	72	90	108	500	600								50 V													
SL1411A090																										
SL1011A145	116	145	174	500	650																					
SL1011B145																										
SL1011A150	120	150	180	500	650																					
SL1011B150										SL1011A:	SI 1011A-	SI 1011A-														
SL 1011R230	19/	230	070	550	700																					
SL 1/11A230	104	230	270	550	700					(@5kA)	5 A	20 A		SL1011B												
SL 1011A250							15 nF	~20.1/	300	(0,)				&	1 k Δ											
SI 1011B250	200	250	300	600	800		1.0 pi	201	shots	SL1011B &	SL1011B &	SL1011B &		SL1411A:	1.0.											
SI 1411A250	200	200	000			1010 0				10 shots	10 A	65 A														
SL1011A260						(at 100V)				(@10kA)																
SL1011B260	210	210 260 310	310	600	800	,																				
SL1011A350																								135 V		
SL1011B350	280	350	420	800	900																					
SL1411A350																										
SL1011A400	320	400	480	850	1000																					
SL1011A470	0 376 470 5			4000	1100	1																				
SL1411A470		564	1000	1100																						
SL1011A500	400	500	600	1100	1200																					
SL1011A600	180	600	720	1200	1400																					
SL1411A600	400	000	120	1200	1400																					

Notes:

1. At delivery AQL 0.65 level II, DIN ISO 2859

2. In ionized mode

3. Comparable to the silicon measurement Switching Voltage (Vs)

4. Tested according to ITU-T Rec. K.12 < 150 msecs.

Product Characteristics

Materials	Leaded Device: Nickel-plated with Tin- plated wires Core and Surface Mount: Dull Tin-plated
Product Marking	Littelfuse 'LF' Mark, voltage and date code

Glow to Arc Transition Current	< 0.5 Amps
Glow Voltage	~60 Volts
Storage and Operational Temperature	-40 to +90°C



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Device Dimensions

For SL1011A/SL1011B series:

'A' Type Axial Lead Devices





For SL1411A series:

'A' Type Axial Lead Devices



'C' Type Core Devices



'SM' Type Surface Mount Devices





Soldering Parameters - Reflow Soldering (Surface Mount Devices)

Reflow Co	ndition	Pb-free assembly		
	-Temperature Min (T _{s(min)})	150°C		
Pre Heat	-Temperature Max (T _{s(max)})	200°C		
	-Time (Min to Max) (t _s)	60 – 180 seconds		
Average R (T _L) to pea	amp-up Rate (LiquidusTemp k)	3°C/second max.		
$T_{S(max)}$ to T_L	- Ramp-up Rate	5°C/second max.		
Reflow	-Temperature (T _L) (Liquidus)	217°C		
	- Temperature (t _L)	60 – 150 seconds		
PeakTemp	erature (T _P)	260 ^{+0/-5} °C		
Time with Temperatu	in 5°C of Actual Peak ıre (t _p)	10 – 30 seconds		
Ramp-dov	vn Rate	6°C/second max.		
Time 25°C	to Peak Temperature (T _P)	8 minutes max.		
Do not exc	ceed	260°C		



Soldering Parameters - Wave Soldering (Thru-Hole Devices)



Recommended Process Parameters:

Wave Parameter	Lead-Free Recommendation
Preheat: (Depends on Flux Activation Temperature)	(Typical Industry Recommendation)
Temperature Minimum:	100° C
Temperature Maximum:	150° C
Preheat Time:	60-180 seconds
Solder Pot Temperature:	280° C Maximum
Solder Dwell Time:	2-5 seconds

Soldering Parameters - Hand Soldering

Solder Iron Temperature: 350° C +/- 5°C Heating Time: 5 seconds max.



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Packaging Dimensions

For 'A' Type Axial Lead Items



For 'SM' Type Surface Mount Items (SL1411A series only)



For 'C' Type Core Items: Packed in plastic bag (500 pcs)



Part Numbering System and Ordering Information

For SL1011A series:

SL1011A XXX X Voltage —— **Pin Configuration** -A = Axial Lead C = Core

Remarks: Formed leads are available on request

For SL1011B series:



Remarks: Formed leads are available on request

For SL1411A series:



Pin Configuration -

A = Axial Lead C = Core

SM = Surface Mount